



SOT407-1

LQFP100, plastic low profile quad flat package; 100 leads; 0.5 mm pitch, 14 mm x 14 mm x 1.4 mm body

1 February 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP100
Package type industry code	LQFP100
Package style descriptive code	LQFP (low profile quad flat package)
Package body material type	P (plastic)
IEC package outline code	136E20
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-02-2003
Manufacturer package code	98ASA01402D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	13.9	14	14.1	mm
package width	13.9	14	14.1	mm
seated height	-	1.6	-	mm
package height	1.35	1.4	1.45	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	100	-	



2 Package outline

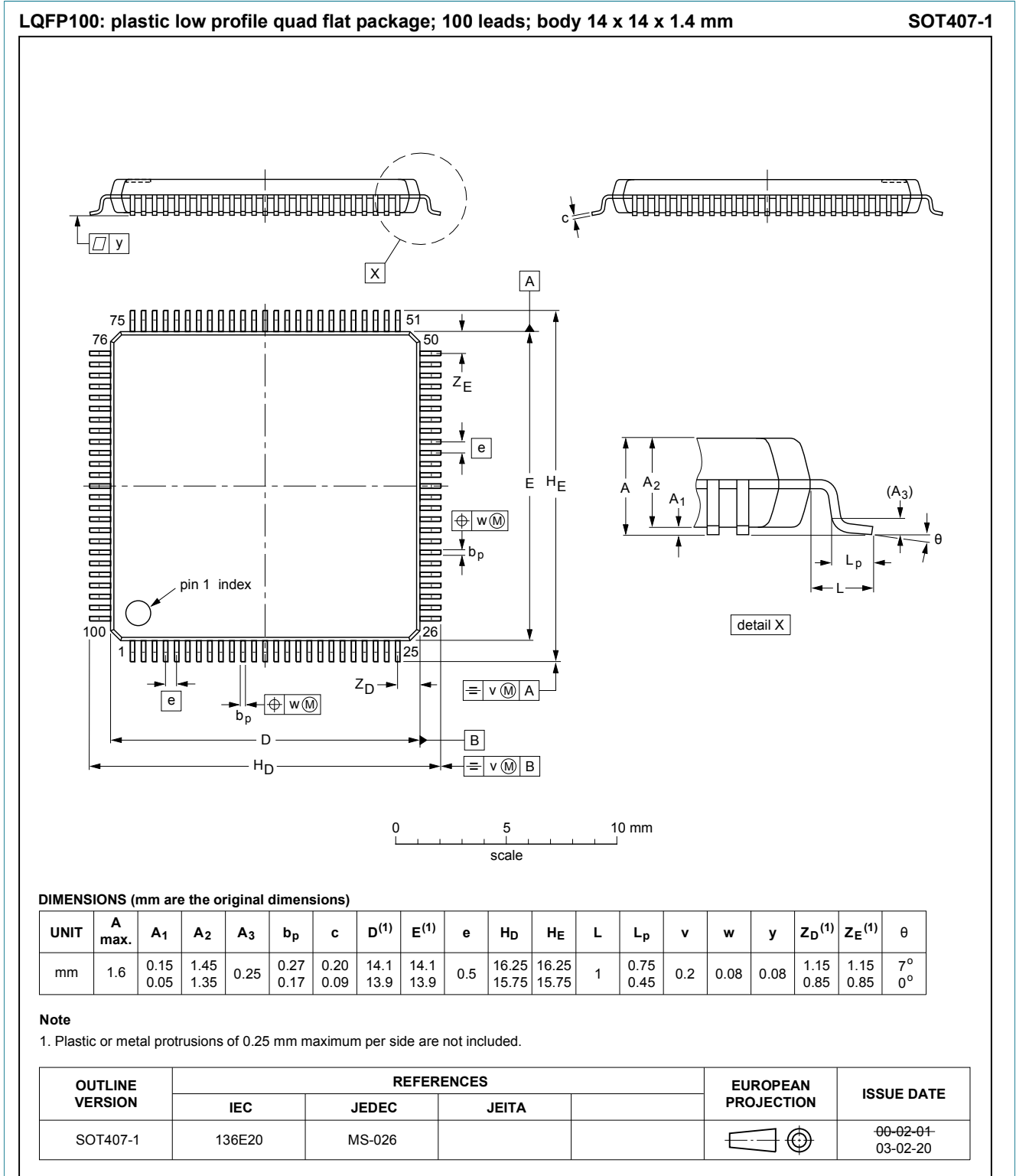


Figure 1. Package outline LQFP100 (SOT407-1)

3 Soldering

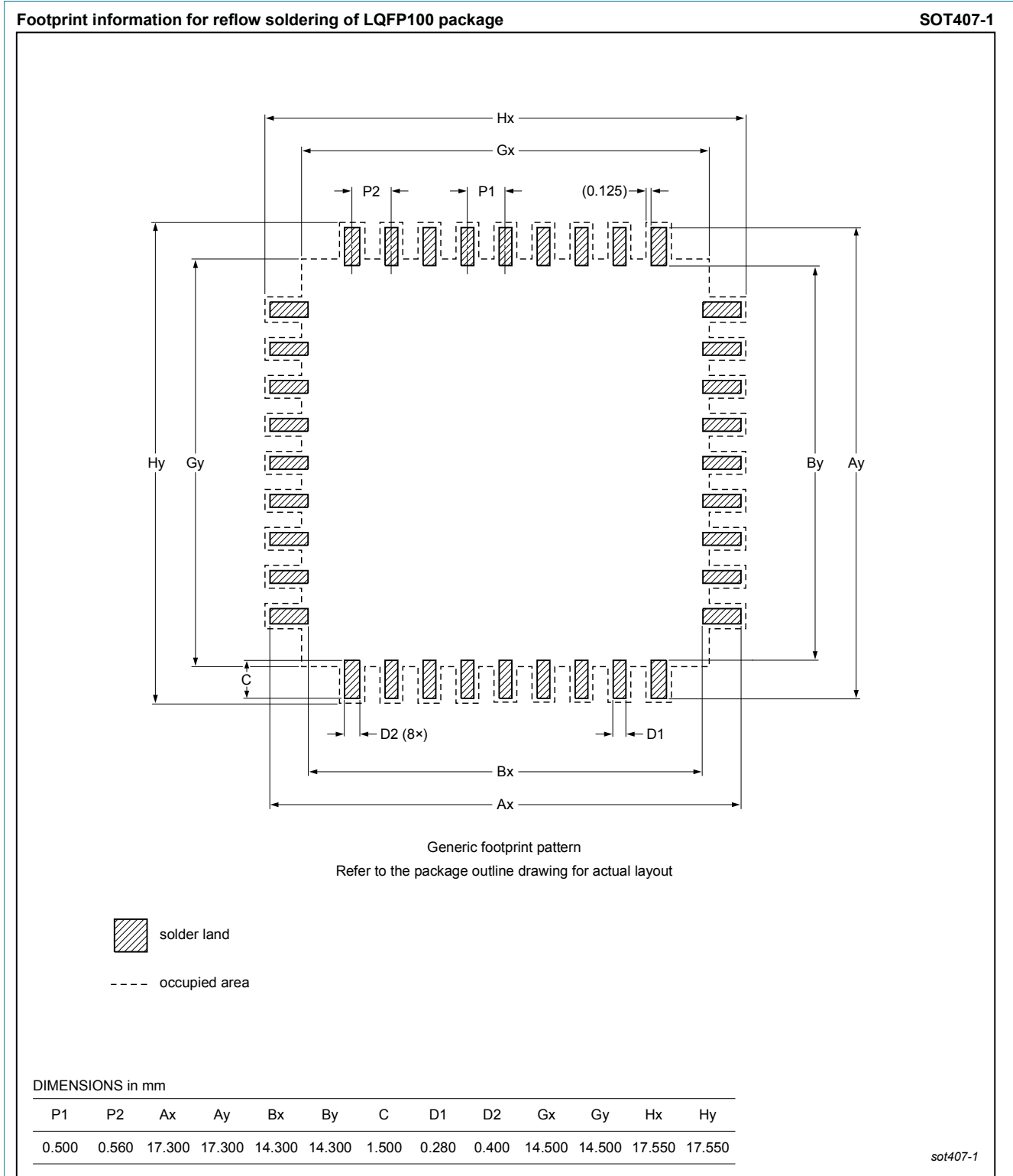


Figure 2. Reflow soldering footprint for LQFP100 (SOT407-1)

4 Legal information

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